

FIG. 1

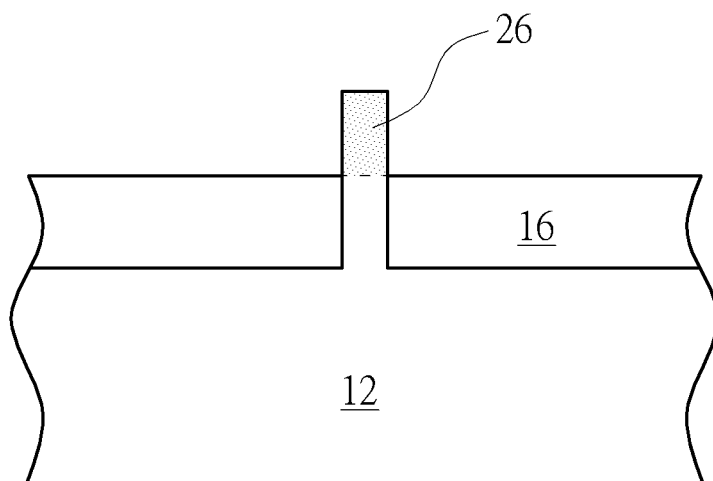


FIG. 2

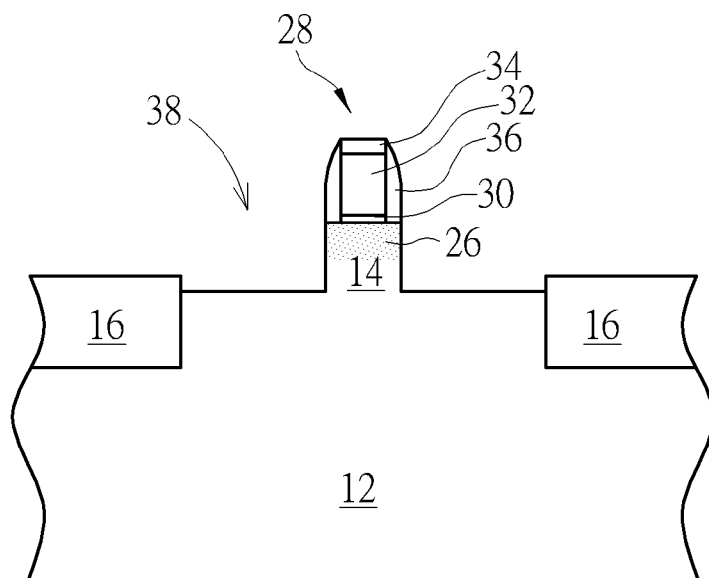


FIG. 3

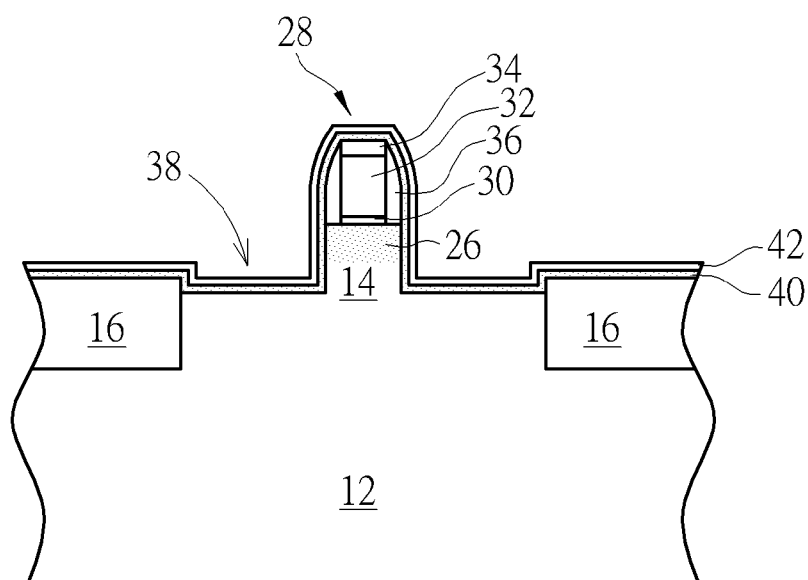


FIG. 4

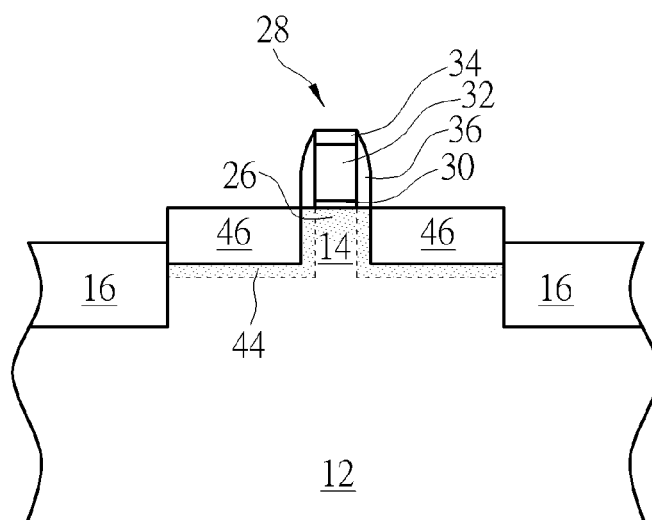


FIG. 5

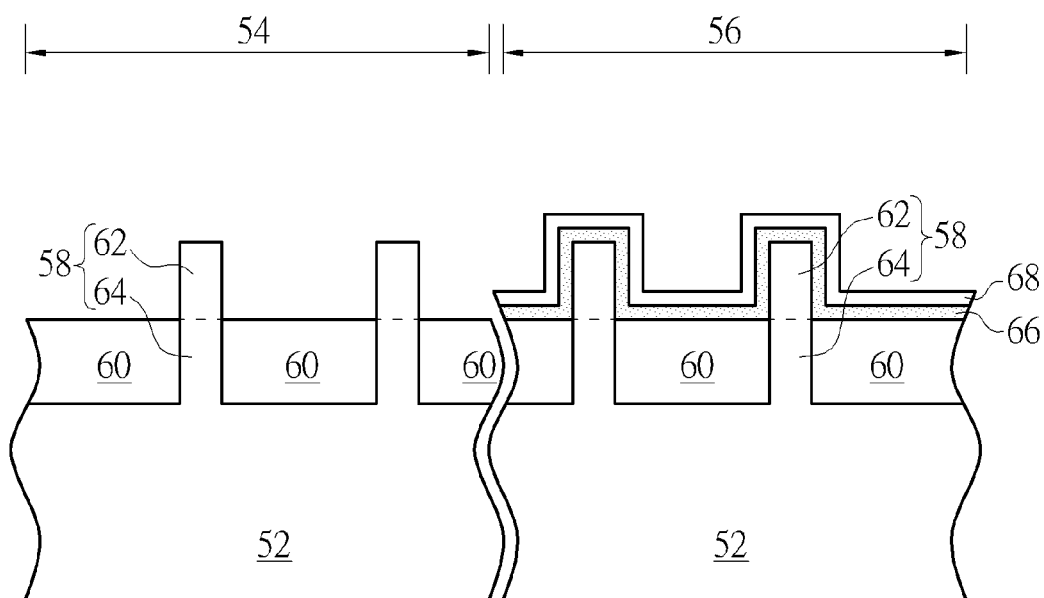


FIG. 6

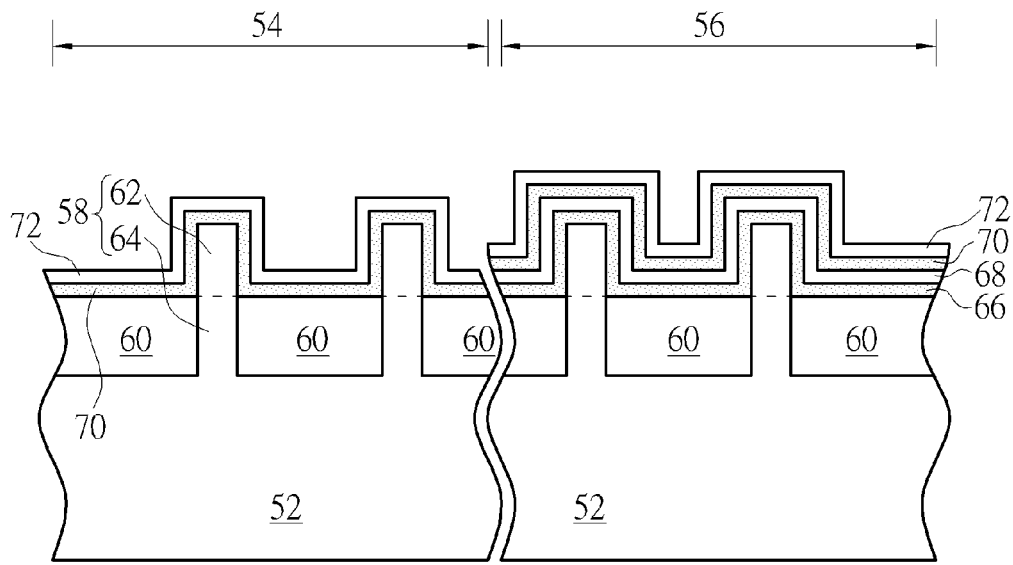


FIG. 7

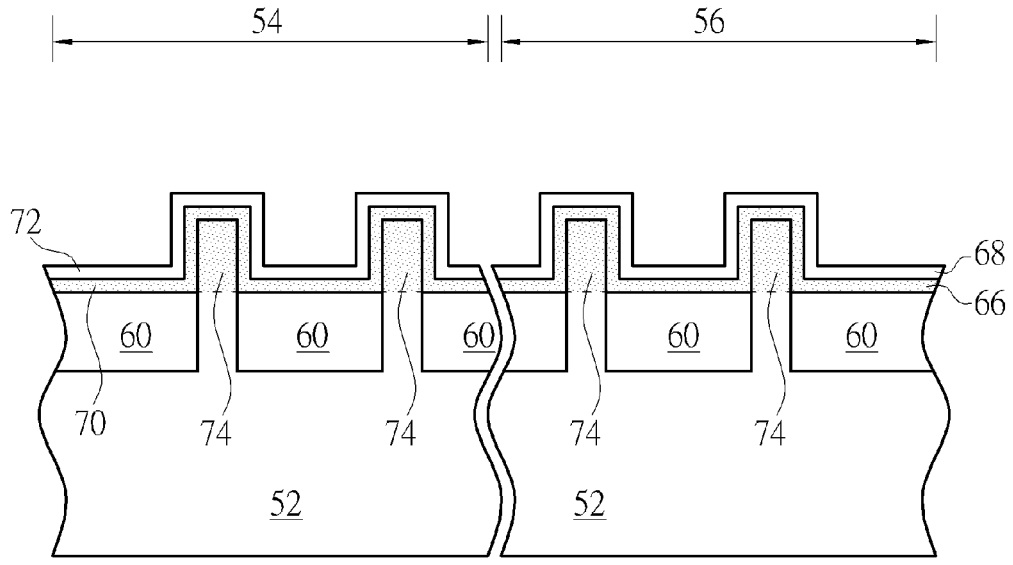


FIG. 8

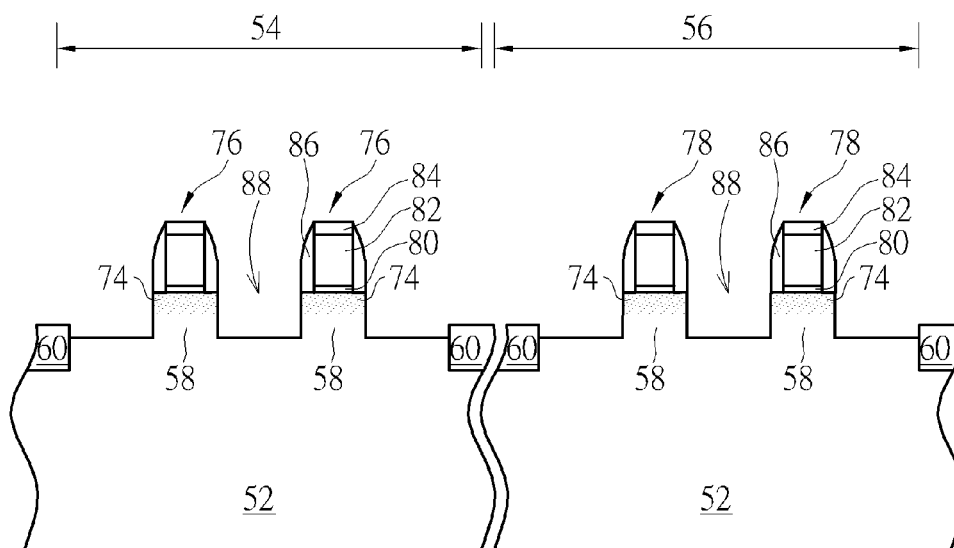


FIG. 9

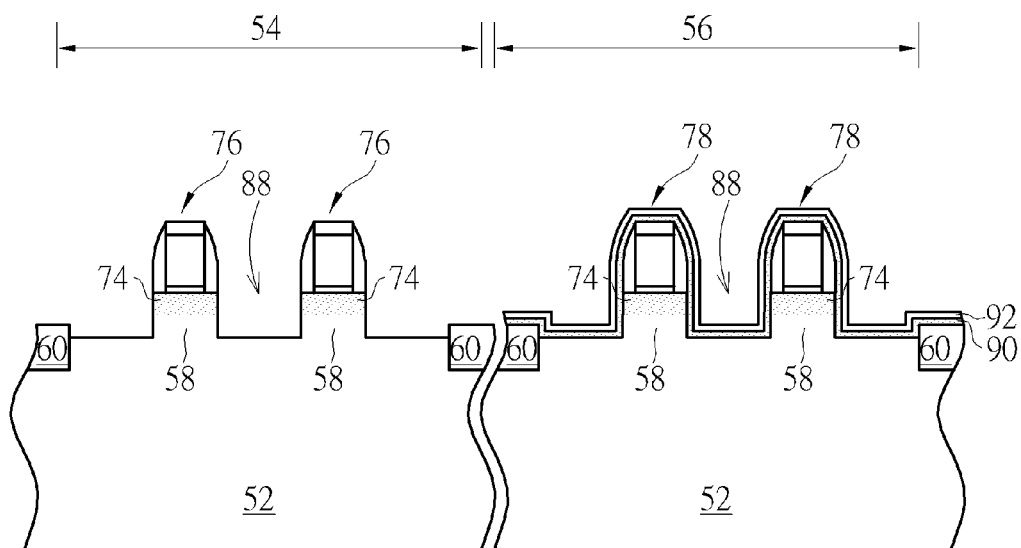


FIG. 10

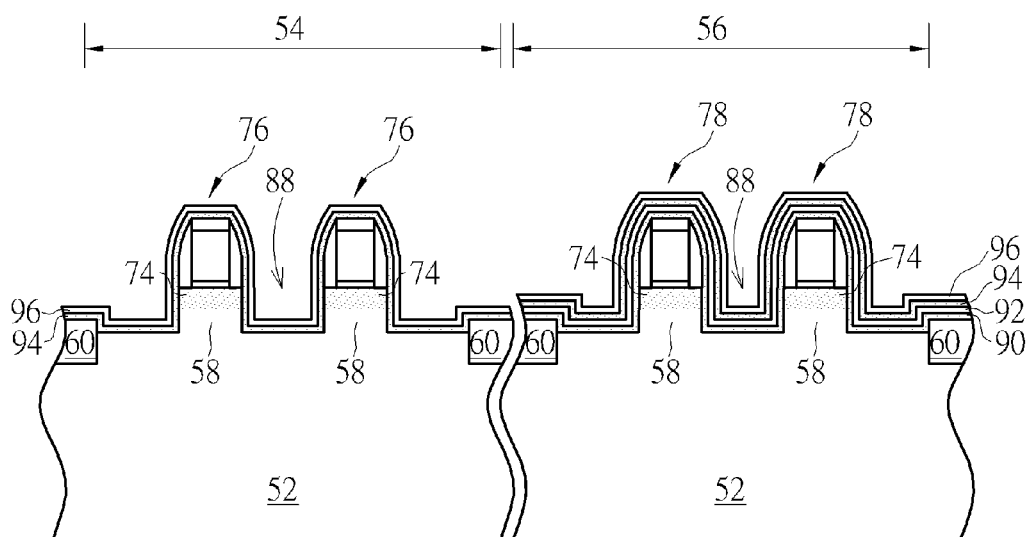


FIG. 11

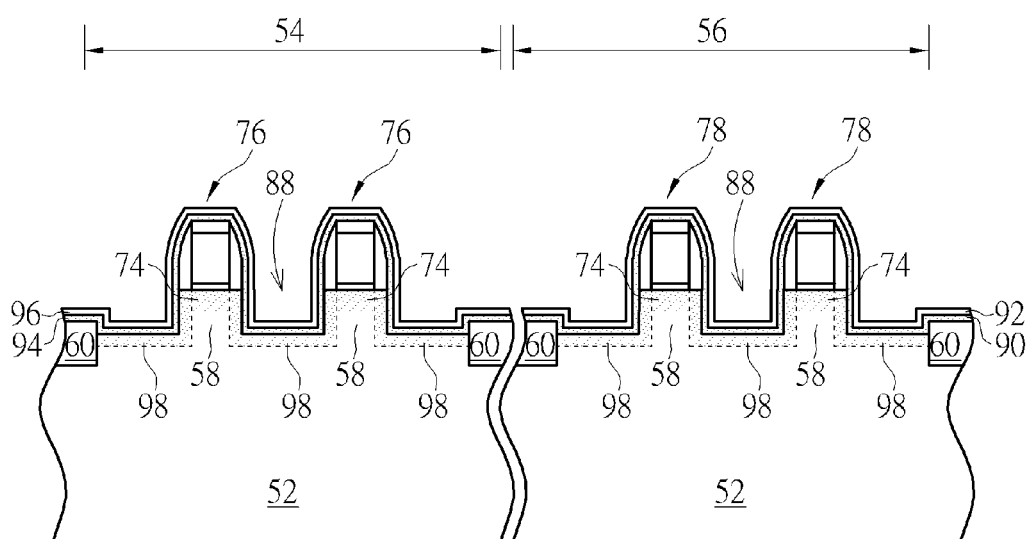


FIG. 12

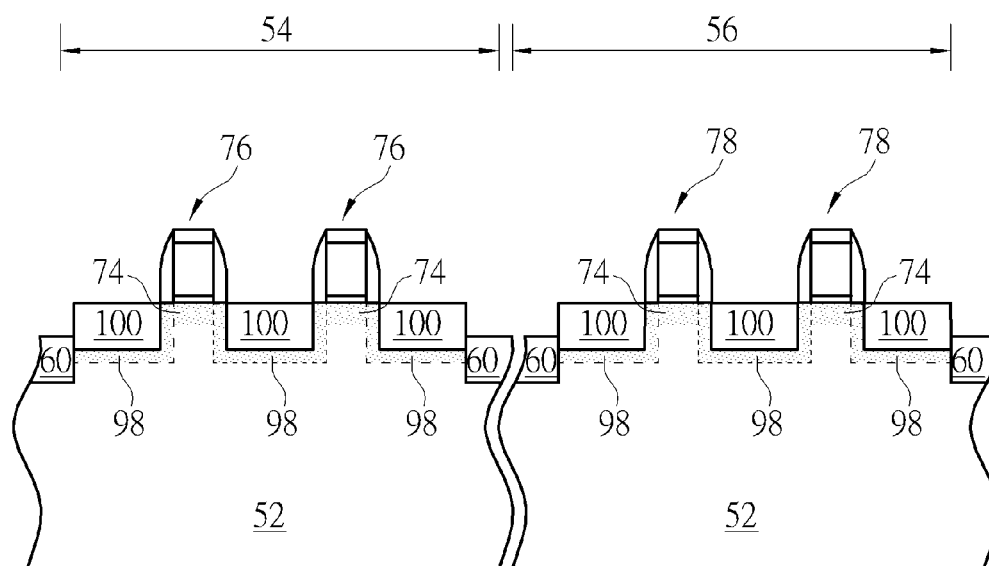


FIG. 13

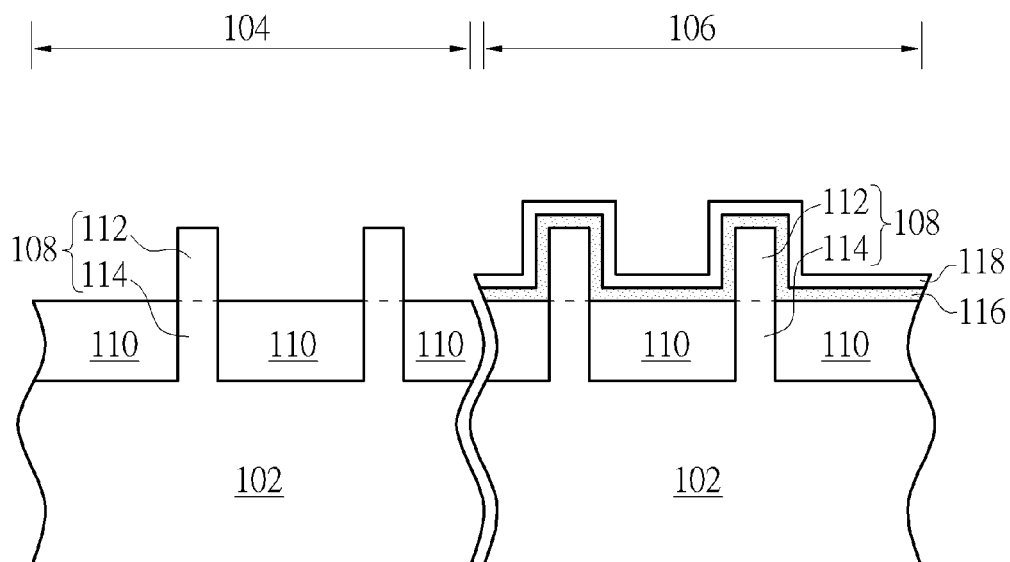


FIG. 14



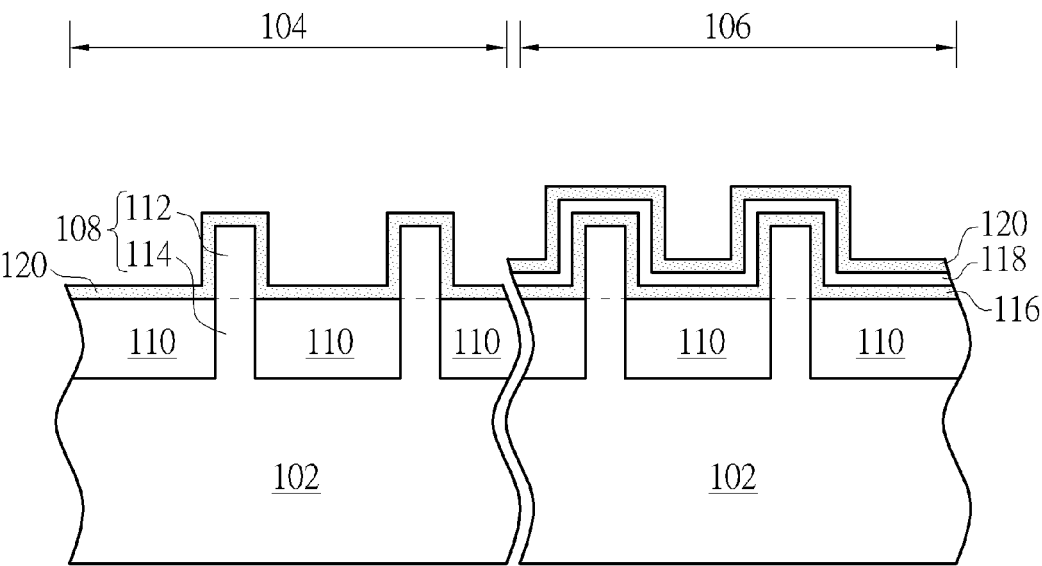


FIG. 15

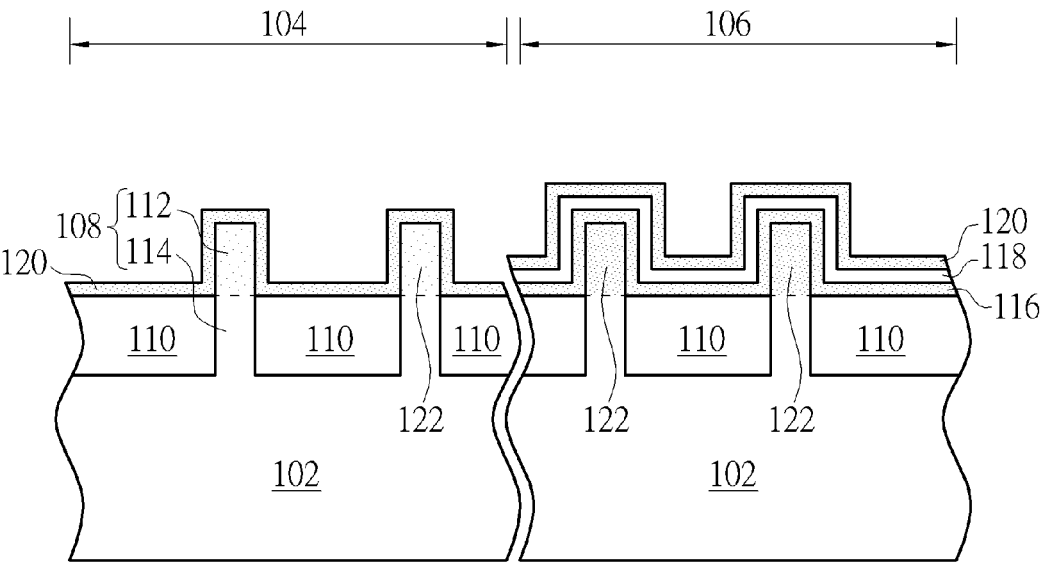


FIG. 16

## METHOD FOR FABRICATING SEMICONDUCTOR DEVICE

### CROSS REFERENCE TO RELATED APPLICATIONS

**[0001]** This is a continuation application of U.S. patent application Ser. No. 14/884,746, filed on Oct. 15, 2015, and all benefits of such earlier application are hereby claimed for this new continuation application.

### BACKGROUND OF THE INVENTION

**[0002]** 1. Field of the Invention

**[0003]** The invention relates to a method for fabricating semiconductor device, and more particularly, to an approach of utilizing solid state doping (SSD) technique to form doped region on the top portion of fin-shaped structure.

**[0004]** 2. Description of the Prior Art

**[0005]** With the trend in the industry being towards scaling down the size of the metal oxide semiconductor transistors (MOS), three-dimensional or non-planar transistor technology, such as fin field effect transistor technology (FinFET) has been developed to replace planar MOS transistors. Since the three-dimensional structure of a FinFET increases the overlapping area between the gate and the fin-shaped structure of the silicon substrate, the channel region can therefore be more effectively controlled. This way, the drain-induced barrier lowering (DIBL) effect and the short channel effect are reduced. The channel region is also longer for an equivalent gate length, thus the current between the source and the drain is increased. In addition, the threshold voltage of the fin FET can be controlled by adjusting the work function of the gate.

**[0006]** However, the design of fin-shaped structure in current FinFET fabrication still resides numerous bottlenecks which induces current leakage of the device and affects overall performance of the device. Hence, how to improve the current FinFET fabrication and structure has become an important task in this field.

### SUMMARY OF THE INVENTION

**[0007]** According to a preferred embodiment of the present invention, a method for fabricating semiconductor device is disclosed. The method includes the steps of: providing a substrate having a fin-shaped structure thereon and a shallow trench isolation (STI) around the fin-shaped structure, in which the fin-shaped structure has a top portion and a bottom portion; forming a first doped layer on the STI and the top portion; and performing a first anneal process.

**[0008]** According to another aspect of the present invention, a method for fabricating semiconductor device is disclosed. The method includes the steps of: providing a substrate having a first region and a second region; forming a first fin-shaped structure on the first region and a second fin-shaped structure on the second region; forming a shallow trench isolation (STI) around the first fin-shaped structure and the second fin-shaped structure so that each of the first fin-shaped structure and the second fin-shaped structure is divided into a top portion and a bottom portion; forming a first doped layer on the STI and the top portion of the second fin-shaped structure; forming a second doped layer on the STI and the top portion of the first fin-shaped structure; and performing a first anneal process.

**[0009]** According to another aspect of the present invention, a method for fabricating semiconductor device is disclosed. The method includes the steps of: providing a substrate having a first region and a second region; forming

a first fin-shaped structure on the first region and a second fin-shaped structure on the second region; forming a shallow trench isolation (STI) around the first fin-shaped structure and the second fin-shaped structure so that each of the first fin-shaped structure and the second fin-shaped structure is divided into a top portion and a bottom portion; forming a first doped layer on the STI and on the top portion of the second fin-shaped structure; forming a second doped layer on the STI and the top portion of the first fin-shaped structure, in which the first doped layer and the second doped layer comprise dopants of same type; and performing an anneal process.

**[0010]** These and other objectives of the present invention will no doubt become obvious to those of ordinary skill in the art after reading the following detailed description of the preferred embodiment that is illustrated in the various figures and drawings.

### BRIEF DESCRIPTION OF THE DRAWINGS

**[0011]** FIGS. 1-5 illustrate a method for fabricating semiconductor device according to a first embodiment of the present invention.

**[0012]** FIGS. 6-13 illustrate a method for fabrication semiconductor device according to a second embodiment of the present invention.

**[0013]** FIGS. 14-16 illustrate a method for fabricating semiconductor device according to a third embodiment of the present invention.

### DETAILED DESCRIPTION

**[0014]** Referring to FIGS. 1-5, FIGS. 1-5 illustrate a method for fabricating semiconductor device according to a first embodiment of the present invention. As shown in FIG. 1, a substrate 12, such as a silicon substrate or silicon-on-insulator (SOI) substrate is provided, and a transistor region, such as a PMOS region or a NMOS region is defined on the substrate 12. At least a fin-shaped structure 14 is formed on the substrate 12 and a shallow trench isolation (STI) 16 is formed around the fin-shaped structure 14.

**[0015]** The formation of the fin-shaped structures 14 could be accomplished by first forming a patterned mask (now shown) on the substrate, 12, and an etching process is performed to transfer the pattern of the patterned mask to the substrate 12. Alternatively, the formation of the fin-shaped structure 14 could also be accomplished by first forming a patterned hard mask (not shown) on the substrate 12, and then performing an epitaxial process on the exposed substrate 12 through the patterned hard mask to grow a semiconductor layer. This semiconductor layer could then be used as the corresponding fin-shaped structures 14. Moreover, if the substrate 12 were a SOI substrate, a patterned mask could be used to etch a semiconductor layer on the bottom oxide layer without etching through the semiconductor layer for forming the fin-shaped structure 14.

**[0016]** The formation of the STI 16 could be accomplished by first depositing an insulating material (not shown) composed of silicon oxide on the substrate 12 to cover the fin-shaped structure 14, and a planarizing process such as chemical mechanical polishing (CMP) process is conducted to remove part of the insulating material or even part of the fin-shaped structure 14 so that the top surface of the remaining insulating material is even with the top surface of the fin-shaped structure 14 to form a STI 16. An etching process is then conducted thereafter to remove part of the STI 16 so that the top surface of the STI 16 is slightly lower than the top surface of the fin-shaped structure 14. This divides the

fin-shaped structure **14** into a top portion **18** and a bottom portion **20**, in which the top surface of the STI **16** is even with the bottom surface of the top portion **18** of fin-shaped structure **14**.

[0017] Next, a doped layer **22** is formed to cover the STI **16** and the top portion **18** of fin-shaped structure **14**, and a liner **24** or cap layer could be selectively formed on the doped layer **22**. In this embodiment, the liner **24** is preferably composed of silicon nitride, and the material of the doped layer **22** could be adjusted depending on the type of transistor being fabricated afterwards. For instance, if a PMOS transistor were to be fabricated, the doped layer **22** is preferably composed of thin film containing p-type dopants, such as borosilicate glass (BSG). Conversely, if a NMOS transistor were to be fabricated, the doped layer **22** is preferably composed of thin film containing n-type dopants, such as phosphosilicate glass (PSG).

[0018] Next, as shown in FIG. 2, an anneal process is conducted to drive dopants within the doped layer **22** into the top portion **18** for forming a doped region **26**, in which the doped region **26** could be used to adjust the threshold voltage of the entire device. The liner **24** and the doped layer **22** are removed thereafter.

[0019] Next, as shown in FIG. 3, a gate structure **28** is formed on the substrate **12** and the fin-shaped structure **14**. In this embodiment, the formation of the gate structure **28** could be accomplished by sequentially forming an interfacial layer, a gate material layer, and a hard mask layer on the substrate **12** to cover the fin-shaped structure **14**, and then using a patterned mask to remove part of the hard mask layer, part of the gate material layer, and part of the interfacial layer. This forms a gate structure **28** composed of an interfacial layer **30**, gate electrode **32**, and hard mask **34**. In this embodiment, the interfacial layer **30** is preferably a silicon layer composed of SiO<sub>2</sub>, SiN, or SiON, but could also be composed of high-k dielectric material. The gate electrode **32** is preferably composed of polysilicon, and the hard mask **34** is selected from the group consisting of silicon oxide and silicon nitride.

[0020] It should be noted that in order to clearly express the relative location of the lightly doped drain formed thereafter and the gate structure **28**, FIG. 3 is preferably a cross-sectional view illustrated along the longer axis of fin-shaped structure **14** while FIGS. 1-2 are cross-sectional views illustrated along the shorter axis of fin-shaped structure **14**.

[0021] Next, a spacer **36** is formed on the sidewall of the gate structure **28**, in which the spacer **36** could be selected from the group consisting of silicon oxide, silicon nitride, silicon oxynitride, and silicon carbon nitride, but not limited thereto. Next, an etching process is conducted to remove part of the fin-shaped structure **14** adjacent to two sides of the spacer **36** for forming a recess **38**.

[0022] Next, as shown in FIG. 4, another doped layer **40** and a selective liner **42** are formed on the fin-shaped structure **14**, STI **16**, and gate structure **28** and filled into the recess **38** without filling the recess **38** completely. Similar to the liner **24** and doped layer **22** from FIG. 1, the liner **42** is preferably composed of silicon nitride, and the material of the doped layer **40** could be adjusted depending on the type of transistor being fabricated afterwards. For instance, if a PMOS transistor were to be fabricated, the doped layer **40** is preferably composed of thin film containing p-type dopants, such as borosilicate glass (BSG). Conversely, if a NMOS transistor were to be fabricated, the doped layer **40** is preferably composed of thin film containing n-type dopants, such as phosphosilicate glass (PSG).

[0023] Next, as shown in FIG. 5, an anneal process is conducted to drive dopants within the doped layer **40** into the fin-shaped structure **14** for forming a doped region **44**, in which the doped region **44** is preferably serving as a lightly doped drain. After removing the liner **42** and the doped layer **40**, an epitaxial layer **46** is formed to fill the recess **38** with in-situ dopants or accompanied by extra ion implantation process to form a source/drain region. Next, standard Fin-FET fabrication process could be conducted by first forming a contact etch stop layer (CESL) on the fin-shaped structure **14** and the gate structure **28** and forming an interlayer dielectric (ILD) layer (not shown) on the CESL. Next, a replacement metal gate (RMG) process is conducted to planarize part of the ILD layer and CESL and transform the gate structure originally composed of polysilicon material into metal gate. Since the RMG process is well known to those skilled in the art, the details of which are not explained herein for the sake of brevity.

[0024] It should be noted that despite two SSD techniques were utilized to adjust threshold voltage and form lightly doped drain in the aforementioned embodiment, including using a doped layer or SSD technique to adjust threshold voltage before formation of gate structure and then using SSD technique again to form lightly doped drain after formation of gate structure, it would also be desirable to conduct either one of the two aforementioned SSD techniques, such as only conducting the SSD technique to adjust threshold voltage before formation of gate structure or only conducting the SSD technique to form lightly doped drain after formation of gate structure, which is also within the scope of the present invention.

[0025] Referring to FIGS. 6-13, FIGS. 6-13 illustrate a method for fabrication semiconductor device according to a second embodiment of the present invention. As shown in FIG. 6, a substrate **52**, such as a silicon substrate or SOI substrate is provided, and a NMOS region **54** and a PMOS region **56** are defined on the substrate **52**. At least a fin-shaped structure **58** is formed on each of the NMOS region **54** and PMOS region **56** and a STI **60** is formed around the fin-shaped structures **58**.

[0026] Similar to the aforementioned first embodiment, the formation of the STI **60** could be accomplished by first depositing an insulating material (not shown) composed of silicon oxide on the substrate **52** to cover the fin-shaped structures **58**, and a planarizing process such as chemical mechanical polishing (CMP) process is conducted to remove part of the insulating material or even part of the fin-shaped structures **58** so that the top surface of the remaining insulating material is even with the top surface of the fin-shaped structures **58** to form a STI **60**. An etching process is then conducted thereafter to remove part of the STI **60** so that the top surface of the STI **60** is slightly lower than the top surface of the fin-shaped structures **58**. This divides each of the fin-shaped structures **58** into a top portion **62** and a bottom portion **64**, in which the top surface of the STI **60** is even with the bottom surface of the top portions **62** of fin-shaped structures **58** on NMOS region **54** and PMOS region **56**. It should also be noted that even though only two fin-shaped structures **58** are formed in each of the NMOS region **54** and PMOS region **56**, the quantity of fin-shaped structures **58** could be adjusted according to the demand of the product.

[0027] Next, a doped layer **66** and a liner **68** serving as hard mask are formed on the STI **60** and covering the fin-shaped structures **58** on NMOS region **54** and PMOS region **56**, in which the liner **68** is preferably composed of

silicon nitride and the doped layer 66 is a material layer composed of p-type dopants, such as BSG.

[0028] Next, the liner 68 and doped layer 66 are removed from the NMOS region 54 by first forming a patterned resist (not shown) on the PMOS region 56, and then conducting an etching process by using the patterned resist as mask to remove the liner 68 and doped layer 66 on the NMOS region 54 for exposing the STI 60 and top portions 62 of fin-shaped structures 58 underneath.

[0029] Next, as shown in FIG. 7, a doped layer 70 and a liner 72 serving as hard mask are formed to cover the fin-shaped structures 58 on NMOS region 54 and the liner 68 on PMOS region 56. Preferably, the liner 72 is composed of silicon nitride and the doped layer 70 is a material layer composed of n-type dopants, such as PSG.

[0030] Next, an anneal process is conducted to drive the n-type dopants from the doped layer 70 and p-type dopants from the doped layer 66 into the top portions 62 of fin-shaped structures 58 on NMOS region 54 and PMOS region 56 respectively. This forms doped regions (not shown) for adjusting the threshold voltage of the device.

[0031] Alternatively, as shown in FIG. 8, it would also be desirable to skip the aforementioned anneal process and first form a patterned resist (not shown) on the NMOS region 54 after doped layer 70 and liner 72 in FIG. 7 are formed, and then conduct an etching process by using the patterned resist as mask to remove the liner 72 and doped layer 70 on PMOS region 56 and expose the liner 68 underneath. An anneal process is conducted thereafter to drive the n-type dopants from doped layer 70 and the p-type dopants from doped layer 66 into the top portions 62 of fin-shaped structures 58 on NMOS region 54 and PMOS region 56 respectively. This forms doped regions 74 for adjusting the threshold voltage of the device.

[0032] Next, an etching process is conducted to completely remove the liners 68 and 72 and doped layers 66 and 70 from NMOS region 54 and PMOS region 56, and as shown in FIG. 9, gate structures 76 are formed on the fin-shaped structures 58 of NMOS region 54 and gate structures 78 are formed on fin-shaped structures 58 of PMOS region 56. Similar to the aforementioned first embodiment, each of the gate structures 76 and 78 includes an interfacial layer 80, a gate electrode 82, and a hard mask 84. Preferably, the interfacial layer 80 is a silicon layer composed of SiO<sub>2</sub>, SiN, or SiON, but could also be composed of high-k dielectric material. The gate electrode 82 is preferably composed of polysilicon, and the hard mask 84 is selected from the group consisting of silicon oxide and silicon nitride. Next, spacers 86 are formed on sidewalls of the gate structures 76 and 78, and an etching process is conducted to remove part of the fin-shaped structures 58 adjacent to the spacers 86 for forming recesses 88, in which the spacers 86 could be selected from the group consisting of silicon oxide, silicon nitride, silicon oxynitride, and silicon carbon nitride, but not limited thereto.

[0033] Similar to the embodiment shown in FIG. 3, in order to clearly express the relative location of the lightly doped drains formed thereafter and the gate structures 76 and 78, FIG. 9 is preferably a cross-sectional view illustrated along the longer axis of fin-shaped structure 14 while FIGS. 6-8 are cross-sectional views illustrated along the shorter axis of fin-shaped structure 14.

[0034] Next, as shown in FIG. 10, another doped layer 90 and a liner 92 are formed on gate structures 76 and 78 of both NMOS region 54 and PMOS region 56 and filled into the recesses 88 without filling the recesses 88 completely. Preferably, the liner 92 is composed of silicon nitride and the

doped layer 90 is a material layer composed of p-type dopants such as BSG. Next, the liner 92 and doped layer 90 are removed from the NMOS region 54 by first forming a patterned resist (not shown) on the PMOS region 56, and an etching process is conducted by using the patterned resist as mask to remove the liner 92 and doped layer 90 from the NMOS region 54 and expose the gate structures 76 and recesses 88 on NMOS region 54.

[0035] Next, as shown in FIG. 11, a doped layer 94 and a liner 96 are formed sequentially to cover the gate structures 76 on NMOS region 54 and the liner 92 on PMOS region 56. Preferably, the liner 96 is composed of silicon nitride and the doped layer 94 is a material layer composed of n-type dopants such as PSG.

[0036] Next, an anneal process is conducted to drive dopants from the doped layers 94 and 90 into the fin-shaped structures 58 adjacent two sides of the gate structures 76 and 78 or fin-shaped structures 58 directly under the recesses 88 on NMOS region 54 and PMOS region 56 for forming doped regions (not shown), in which these doped regions are preferably serving as lightly doped drains for NMOS transistors and PMOS transistors respectively.

[0037] Alternatively, as shown in FIG. 12, it would also be desirable to skip the aforementioned anneal process and first form a patterned resist (not shown) on the NMOS region 54 after doped layer 94 and liner 96 in FIG. 11 are formed, and then conduct an etching process by using the patterned resist as mask to remove the liner 96 and doped layer 94 on PMOS region 56 and expose the liner 92 underneath. An anneal process is conducted thereafter to drive the n-type dopants from doped layer 94 and the p-type dopants from doped layer 90 into the fin-shaped structures 58 adjacent to two sides of the gate structures 76 and 78 or fin-shaped structures 58 under the recesses 88 on NMOS region 54 and PMOS region 56 respectively for forming doped regions 98. Similar to the doped regions formed in FIG. 11, the doped regions 98 are preferably serving as lightly doped drains for NMOS transistors and PMOS transistors.

[0038] Next, as shown in FIG. 13, after removing the liners 92 and 96 and doped layers 90 and 94 from NMOS region 54 and PMOS region 56, epitaxial layers 100 are formed to fill the recesses 88 with in-situ dopants or accompanied by extra ion implantation process to form source/drain regions on NMOS region 54 and PMOS region 56, in which the epitaxial layer 100 filled in the recesses 88 on NMOS region 54 preferably includes epitaxial material containing n-type dopants such as SiC or SiP, whereas the epitaxial layer 100 filled in the recesses 88 on PMOS region 56 preferably includes epitaxial material such as silicon germanium (SiGe) containing p-type dopants. In this embodiment, the formation of the epitaxial layers 100 could be accomplished by first depositing epitaxial material such as SiGe containing p-type dopants into recesses 88 on both NMOS region 54 and PMOS region 56, forming a cap layer (not shown) composed of silicon nitride on the substrate 12 and gate structures 76 and 78 on NMOS region 54 and PMOS region 56, using a patterned resist (not shown) to remove the cap layer and SiGe on NMOS region 54, depositing epitaxial material such as SiC containing n-type dopants into recesses 88 on NMOS region 54, and finally removing the cap layer on PMOS region 56. This completes the formation of a semiconductor device according to second embodiment of the present invention.

[0039] Referring to FIGS. 14-16, FIGS. 14-16 illustrate a method for fabricating semiconductor device according to a third embodiment of the present invention. As shown in FIG.

14, a substrate 102, such as a silicon substrate or SOI substrate is provided, and two transistor regions, such as a first region 104 and a second region 106 are defined on the substrate 12. In this embodiment, the first region 104 and the second region 106 are regions of same conductive type, such as both being PMOS regions or both being NMOS regions, and the first region 104 and second region 106 are defined for forming gate structure having different threshold voltage in the later process. Since this embodiment pertains to the fabrication of PMOS transistors, the first region 104 and second region 106 are both defined as PMOS regions. However, in other embodiment of the present invention, it would also be desirable to define the first region 104 and second region 106 as NMOS regions according to the demand of the product, which is also within the scope of the present invention. Fin-shaped structures 108 are formed on the substrate 102 of the first region 104 and second region 106 respectively, and a STI 110 is formed around the fin-shaped structures 108 on both first region 104 and second region 106.

[0040] Similar to the aforementioned first embodiment, the formation of the STI 110 could be accomplished by first depositing an insulating material (not shown) composed of silicon oxide on the substrate 102 to cover the fin-shaped structures 108, and a planarizing process such as chemical mechanical polishing (CMP) process is conducted to remove part of the insulating material or even part of the fin-shaped structures 108 so that the top surface of the remaining insulating material is even with the top surface of the fin-shaped structures 108 to form a STI 110. An etching process is then conducted thereafter to remove part of the STI 110 so that the top surface of the STI 110 is slightly lower than the top surface of the fin-shaped structures 108. This divides each of the fin-shaped structures 108 into a top portion 112 and a bottom portion 114, in which the top surface of the STI 110 is even with the bottom surface of the top portions 112 of fin-shaped structures 108 on first region 104 and second region 106. It should also be noted that even though only two fin-shaped structures 108 are formed in each of the first region 104 and second region 106, the quantity of fin-shaped structures 108 could be adjusted according to the demand of the product.

[0041] Next, a doped layer 116 and a liner 118 are formed sequentially on the STI 110 to cover the fin-shaped structures 108 on first region 104 and second region 106. Preferably, the liner 118 is composed of silicon nitride and the doped layer 116 is a material layer composed of p-type dopants, such as BSG.

[0042] The liner 118 and doped layer 116 are removed from first region 104 by first forming a patterned resist (not shown) on the second region 106, and an etching process is conducted by using the patterned resist as mask to remove the liner 118 and doped layer 116 on first region 104 to expose the STI 110 and fin-shaped structures 108 underneath.

[0043] Next, as shown in FIG. 15, a doped layer 120 and a selective liner (not shown) are formed to cover the fin-shaped structures 108 on first region 104 and the liner 118 on second region 106. Preferably, the doped layers 120 and 116 are composed of dopants of same conductive type, such as both being BSG, and the dopant concentration of the doped layer 116 is preferably larger than the dopant concentration of the doped layer 120. It should be noted that even though both the doped layers 116 and 120 are material layers containing p-type dopants such as BSG, it would also be desirable to adjust the type of dopants being used depend on the demand of the product. For instance, if NMOS

transistors were fabricated on the first region 104 and second region 106, the doped layers 116 and 120 containing n-type dopants such as PSG could be used.

[0044] Next, as shown in FIG. 16, an anneal process is conducted to drive dopants within the doped layers 116 and 120 into the top portions 112 of fin-shaped structures 108 on first region 104 and second region 106 for forming doped regions 122, and an etching process is conducted to remove the liner 118 and doped layers 116 and 120 from first region 104 and second region 106 completely. This completes the fabrication of a semiconductor device according to a third embodiment of the present invention. It should be noted that since dopants of higher concentration from doped layer 116 are driven into the fin-shaped structures 108 on the second region 106 while dopants of lower concentration from doped layer 120 are driven into the fin-shaped structures 108 on the first region 104, the concentration of the doped regions 122 formed on second region 106 after the anneal process would be higher than the concentration of the doped regions 122 formed on first region 104. In this embodiment, the doped region 122 with higher dopant concentration on second region 106 could be used to fabricate a standard threshold voltage (SVT) gate while the doped region 122 with lower dopant concentration on first region 104 could be used to fabricate a low threshold voltage (LVT) gate in the later processes.

[0045] Overall, the present invention discloses an approach of employing solid state doping (SSD) technique on FinFET devices. Preferably, the aforementioned first embodiment and second embodiment not only could use the SSD technique to drive dopants from the doped layer into the top portion of fin-shaped structure for adjusting threshold voltage and resolving issues such as uneven dopant distribution caused by conventional ion implantation technique, but also could similar SSD technique to form doped regions serving as lightly doped drains in the fin-shaped structure adjacent to the gate structure. Moreover, the third embodiment of the present invention applies similar SSD technique to form doped regions with same conductive type but different dopant concentration on different regions of fin-shaped structure. This allows the formation of gate structures suitable for different threshold voltages in the later process.

[0046] Those skilled in the art will readily observe that numerous modifications and alterations of the device and method may be made while retaining the teachings of the invention. Accordingly, the above disclosure should be construed as limited only by the metes and bounds of the appended claims.

What is claimed is:

1. A method for fabricating semiconductor device, comprising:
  - providing a substrate having a fin-shaped structure thereon and a shallow trench isolation (STI) around the fin-shaped structure, wherein the fin-shaped structure comprises a top portion and a bottom portion;
  - forming a first doped layer on the STI and the top portion; and
  - performing a first anneal process.
2. The method of claim 1, wherein the top surface of the STI is even with the bottom surface of the top portion of the fin-shaped structure.
3. The method of claim 1, wherein the first doped layer comprises borosilicate glass (BSG) or phosphosilicate glass (PSG).

4. The method of claim 1, further comprising:  
 removing the first doped layer;  
 forming a gate structure on the substrate and the fin-shaped structure;  
 removing part of the fin-shaped structure adjacent to the gate structure for forming a recess;  
 forming a second doped layer on the gate structure and in the recess;  
 performing a second anneal process; and  
 removing the second doped layer.

5. The method of claim 4, wherein the second doped layer comprises borosilicate glass (BSG) or phosphosilicate glass (PSG).

6. A method for fabricating semiconductor device, comprising:  
 providing a substrate having a first region and a second region;  
 forming a first fin-shaped structure on the first region and a second fin-shaped structure on the second region;  
 forming a shallow trench isolation (STI) around the first fin-shaped structure and the second fin-shaped structure so that each of the first fin-shaped structure and the second fin-shaped structure is divided into a top portion and a bottom portion;  
 forming a first doped layer on the STI and the top portion of the second fin-shaped structure;  
 forming a second doped layer on the STI and the top portion of the first fin-shaped structure; and  
 performing a first anneal process.

7. The method of claim 6, further comprising:  
 forming the first doped layer and a first liner on the STI, the first fin-shaped structure and the second fin-shaped structure;  
 removing the first liner and the first doped layer from the first region;  
 forming the second doped layer and a second liner on the STI, the first fin-shaped structure and the first liner; and  
 performing the first anneal process.

8. The method of claim 7, further comprising:  
 removing the second liner and the second doped layer from the second region before performing the first anneal process.

9. The method of claim 6, wherein the top surface of the STI is even with the bottom surface of the top portion of the first fin-shaped structure and the bottom surface of the top portion of the second fin-shaped structure.

10. The method of claim 6, wherein the first doped layer comprises borosilicate glass (BSG) and the second doped layer comprises phosphosilicate glass (PSG).

11. The method of claim 6, further comprising:

removing the first doped layer and the second doped layer;

forming a first gate structure on the first fin-shaped structure and a second gate structure on the second fin-shaped structure;

removing part of the first fin-shaped structure adjacent to the first gate structure for forming a first recess and part of the second fin-shaped structure adjacent to the second gate structure for forming a second recess;

forming a third doped layer on the second gate structure and in the second recess;

forming a fourth doped layer on the first gate structure and in the first recess; and

performing a second anneal process.

12. The method of claim 11, further comprising:

forming the third doped layer and a third liner on the first gate structure and the second structure and in the first recess and the second recess;

removing the third liner and the third doped layer from the first region;

forming the fourth doped layer and a fourth liner on the first gate structure and the third liner; and

performing the second anneal process.

13. The method of claim 12, further comprising:

removing the fourth liner and the fourth doped layer from the second region before performing the second anneal process.

14. The method of claim 11, wherein the third doped layer comprises borosilicate glass (BSG) and the fourth doped layer comprises phosphosilicate glass (PSG).

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